CLAIMS

1. An adhesive composition comprising an adhesive component (S) and a release agent component (B) containing a polyorganosiloxane, wherein

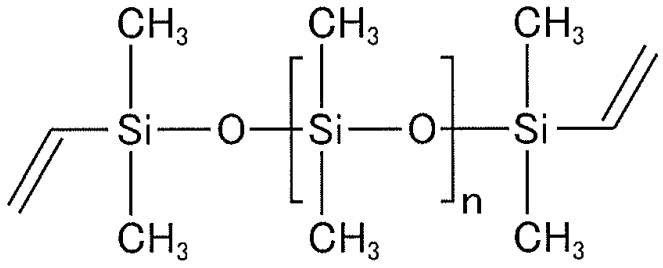
the adhesive component (S) contains a polyorganosiloxane component (A) that is cured by hydrosilylation reaction,

the polyorganosiloxane component (A) contains a polymer (V) represented by formula (V) below and having a weight average molecular weight of 60,000 or more,

a weight average molecular weight of the release agent component (B) is 100,000 to 2,000,000, and

a complex viscosity of the release agent component (B) is 3,400 (Pa · s) or more,

[Chemical Formula 1]



(V)

wherein n represents the number of repeating units, and is a positive integer.

2. The adhesive composition according to claim 1, wherein

the polyorganosiloxane component (A) contains a

polyorganosiloxane (A1) containing one or two or more units selected from the group consisting of a siloxane unit represented by SiO_2 (unit Q), a siloxane unit represented by $R^1R^2R^3SiO_{1/2}$ (unit M), a siloxane unit represented by $R^4R^5SiO_{2/2}$ (unit D), and a siloxane unit represented by $R^6SiO_{3/2}$ (unit T), and a platinum group metal catalyst (A2) (wherein R^1 to R^6 are groups or atoms bonded to a silicon atom, and each independently represent an optionally substituted alkyl group, an optionally substituted alkenyl group, or a hydrogen atom),

the polyorganosiloxane (A1) contains one or two or more units selected from the group consisting of a siloxane unit represented by SiO_2 (unit Q'), a siloxane unit represented by $R^1'R^2'R^3'SiO_{1/2}$ (unit M'), a siloxane unit represented by $R^4'R^5'SiO_{2/2}$ (unit D'), and a siloxane unit represented by $R^6'SiO_{3/2}$ (unit T'), and contains a polyorganosiloxane (a1) containing at least one selected from the group consisting of the unit M', unit D', and unit T', and one or two or more units selected from the group consisting of a siloxane unit represented by SiO_2 (unit Q"), a siloxane unit represented by $R^1"R^2"R^3"SiO_{1/2}$ (unit M"), a siloxane unit represented by $R^4"R^5"SiO_{2/2}$ (unit D"), and a siloxane unit represented by $R^6"SiO_{3/2}$ (unit T"), and contains a polyorganosiloxane (a2) containing at least one selected from the group consisting of the unit M", unit D",

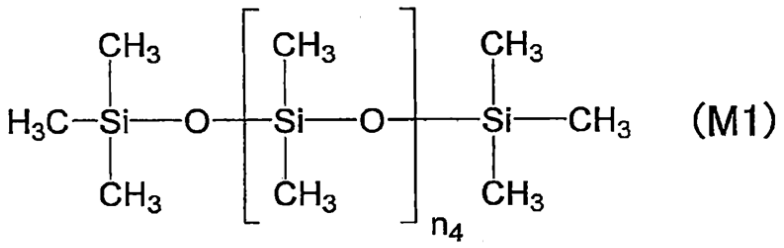
and unit T" (wherein $R^{1'}$ to $R^{6'}$ are groups bonded to a silicon atom, and each independently represent an optionally substituted alkyl group or an optionally substituted alkenyl group, but at least one of $R^{1'}$ to $R^{6'}$ is an optionally substituted alkenyl group, and $R^{1"}$ to $R^{6"}$ are groups or atoms bonded to a silicon atom, and each independently represent an optionally substituted alkyl group or hydrogen atom, but at least one of $R^{1"}$ to $R^{6"}$ is a hydrogen atom), and

the polyorganosiloxane (a1) contains the polymer (V).

3. The adhesive composition according to claim 1 or 2, wherein the weight average molecular weight of the polymer (V) is 100,000 or more.

4. The adhesive composition according to claim 1, wherein the release agent component (B) is a polyorganosiloxane represented by formula (M1) below:

[Chemical Formula 2]



(M1)

wherein n_4 represents the number of repeating units, and is a positive integer.

5. A laminate comprising an adhesive layer interposed between a semiconductor substrate with bumps and a support substrate and in contact with the semiconductor substrate, wherein

the adhesive layer is a layer formed from the adhesive composition according to any one of claims 1 to 4.

6. A method for producing a semiconductor substrate, comprising the steps of:

processing the semiconductor substrate in the laminate according to claim 5; and

separating the support substrate and the processed semiconductor substrate from each other.

7. A method for producing a laminate that produces the laminate according to claim 5, comprising the steps of:

forming an adhesive coating layer that provides the adhesive layer; and

heating the adhesive coating layer to form the adhesive layer.